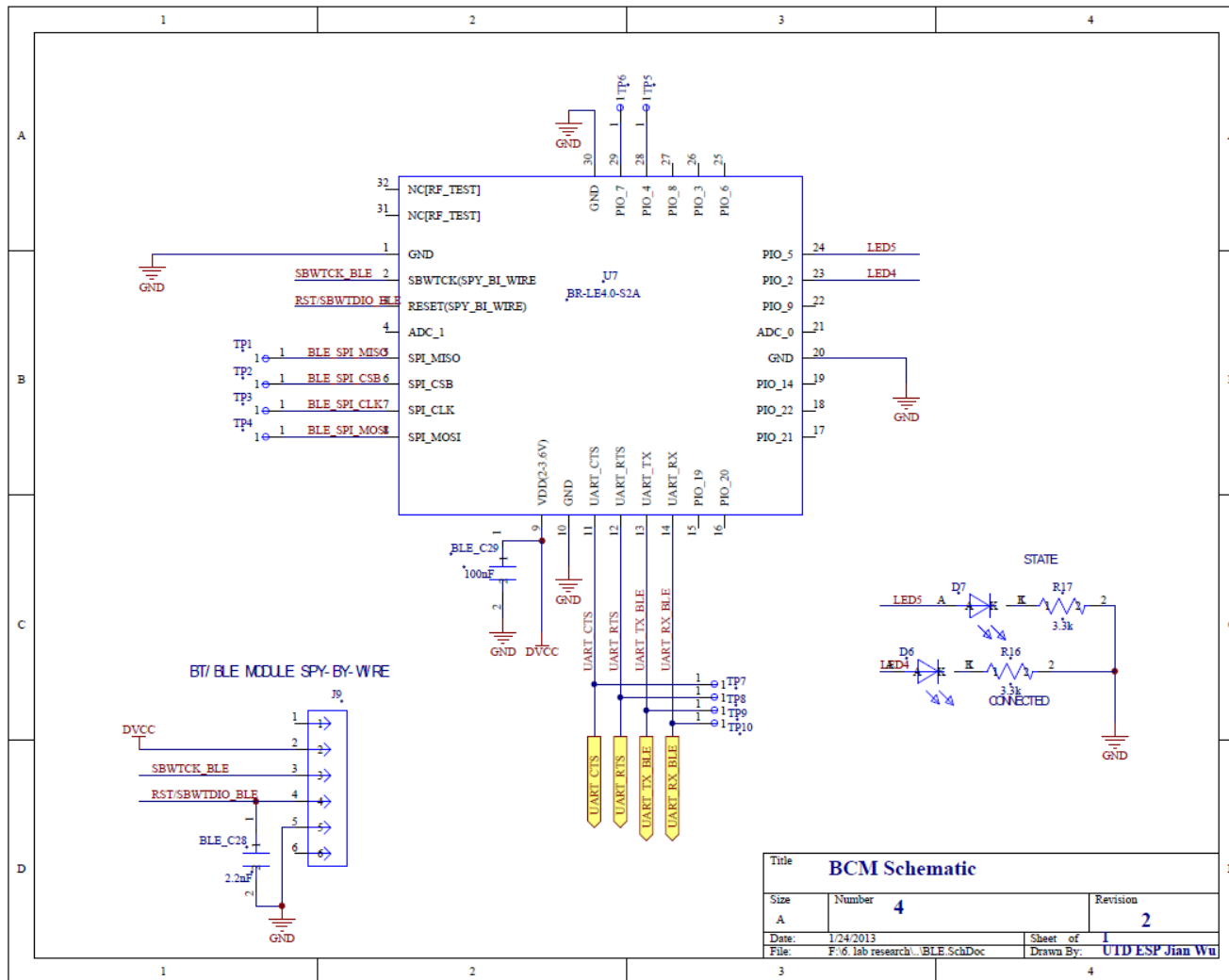
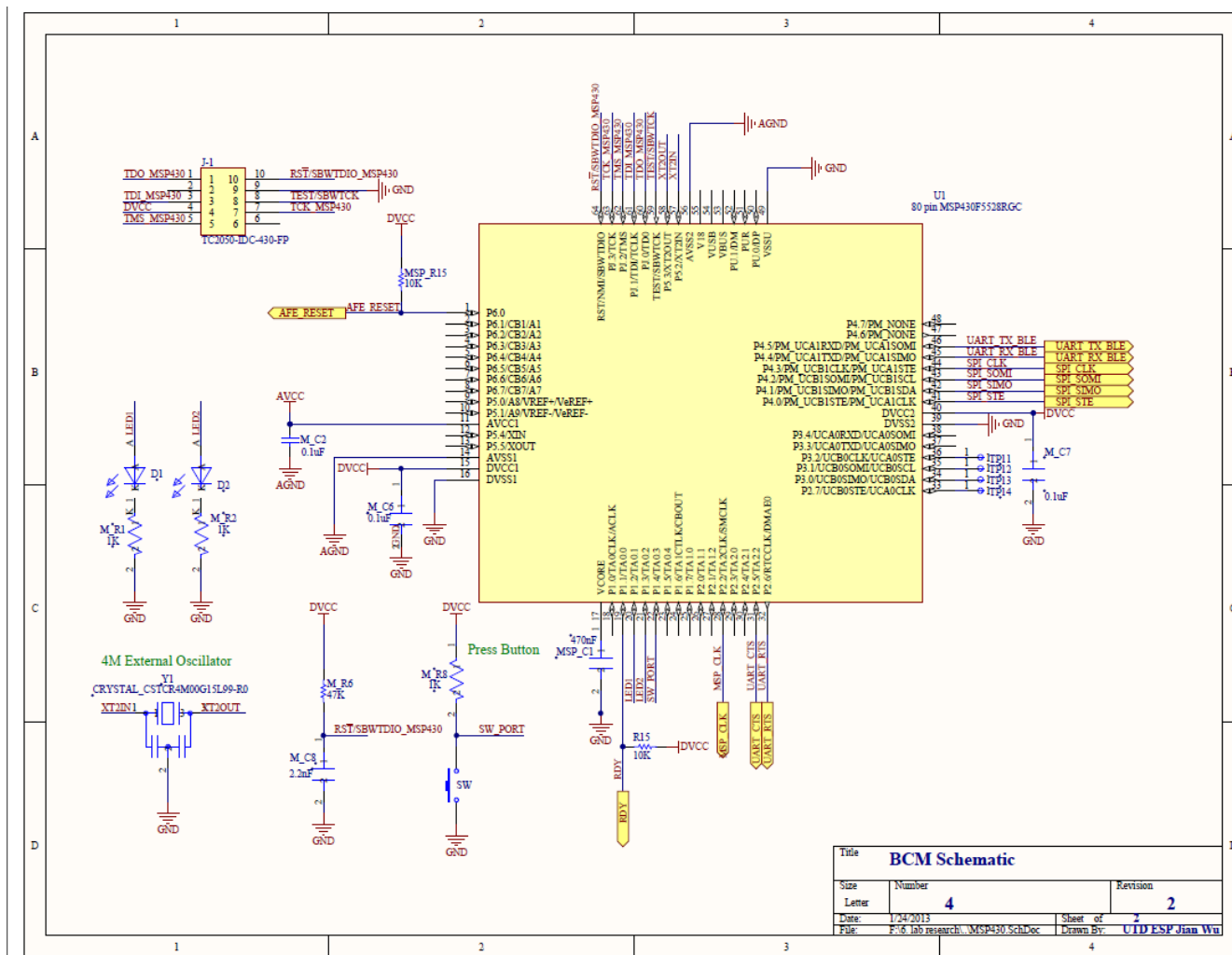


TI Designs: Body Weight Scale Reference Design with Body Composition capability and BLE Connectivity



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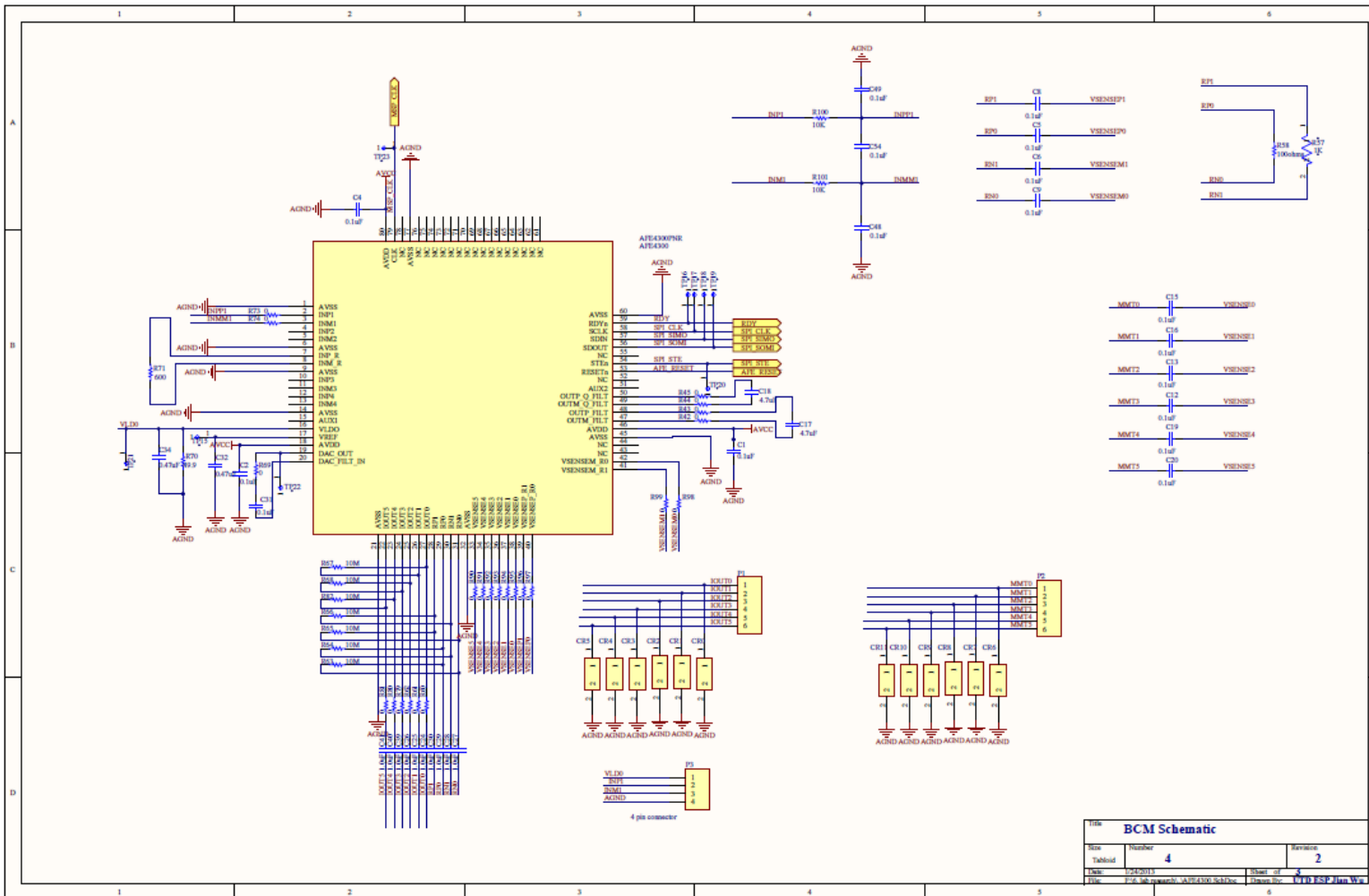
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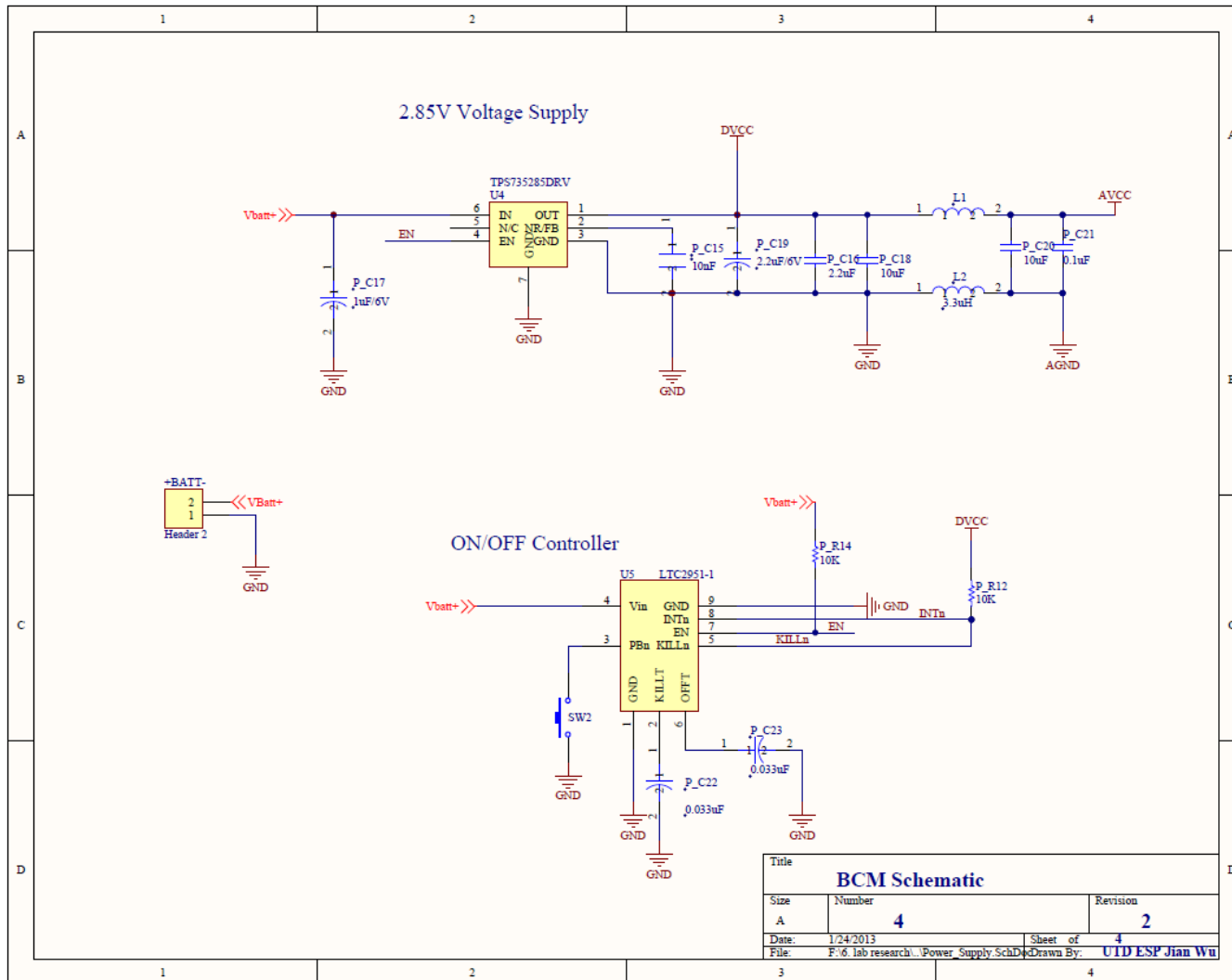
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Title		
BCM Schematic		
Size	Number	Revision
A	4	2
Date:	1/24/2013	Sheet of 4
File:	F:\6_lab_research\Power_Supply.SchDoc	Drawn By: UID ESP Jian Wu

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